DATA SHEET

For a complete data sheet, please also download:

• The IC06 74HC/HCT/HCU/HCMOS Logic Family Specifications

74HC/HCT40105

4-bit x 16-word FIFO register

Philips
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4-bit x 16-word FIFO register

74HC/HCT40105

FEATURES

- Independent asynchronous inputs and outputs
- Expandable in either direction
- Reset capability
- Status indicators on inputs and outputs
- 3-state outputs
- Output capability: standard
- I_{CC} category: MSI

GENERAL DESCRIPTION

The 74HC/HCT40105 are high-speed Si-gate CMOS devices and are pin compatible with the "40105" of the "4000B" series. They are specified in compliance with JEDEC standard no. 7A.

The 74HC/HCT40105 are first-in/first-out (FIFO) "elastic" storage registers that can store sixteen 4-bit words. The "40105" is capable of handling input and output data at different shifting rates. This feature makes it particularly useful as a buffer between asynchronous systems. Each word position in the register is clocked by a control flip-flop, which stores a marker bit. A "1" signifies that the position's data is filled and a "0" denotes a vacancy in that position. The control flip-flop detects the state of the preceding flip-flop and communicates its own status to the succeeding flip-flop. When a control flip-flop is in the "0" state and sees a "1" in the preceding flip-flop, it generates a clock pulse that transfers data from the preceding four data latches into its own four data latches and resets the preceding flip-flop to "0". The first and last control flip-flops have buffered outputs. Since all empty locations "bubble" automatically to the input end, and all valid data ripples through to the output end, the status of the first control flip-flop (data-in ready output - DIR) indicates if the FIFO is full, and the status of the last flip-flop (data-out ready output - DOR) indicates if the FIFO contains data. As the earliest data is removed from the bottom of the data stack (output end), all data entered later will automatically ripple toward the output.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; t_r = t_f = 6 ns

SYMBOL	PARAMETER	CONDITIONS	TYP.		UNIT
			HC	HCT	
t_{PHL}/ t_{PLH}	propagation delay	C_L = 15 pF; V_{CC} = 5 V			
	MR to DIR, DOR		16	15	ns
	$\overline{SO}$ to Q_n		37	35	ns
t_{PHL}	propagation delay				
	SI to DIR		16	18	ns
	$\overline{SO}$ to DOR		17	18	ns
f_{max}	maximum clock frequency		33	31	MHz
C_I	input capacitance		3.5	3.5	pF
C_{PD}	power dissipation capacitance per package	notes 1 and 2	134	145	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

    $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

    f_i = input frequency in MHz.

    f_o = output frequency in MHz.

    $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs

    C_L = output load capacitance in pF

    V_{CC} = supply voltage in V

2. For HC the condition is V_I = GND to V_{CC}
   For HCT the condition is V_I = GND to $V_{CC} - 1.5$
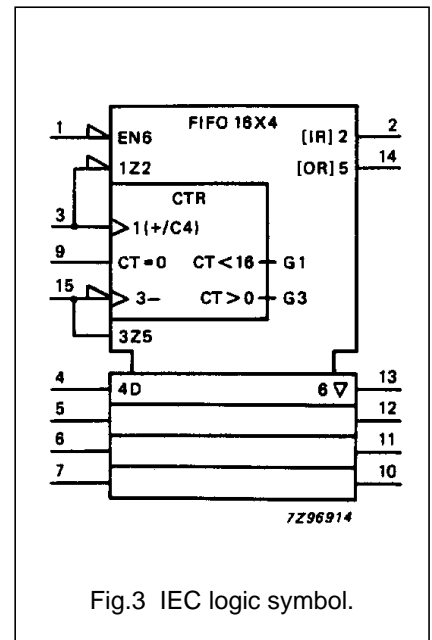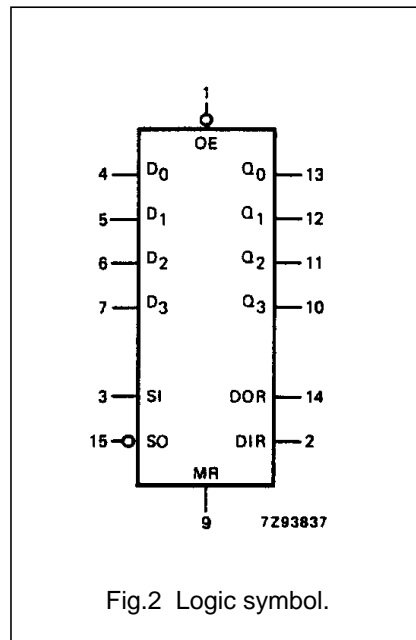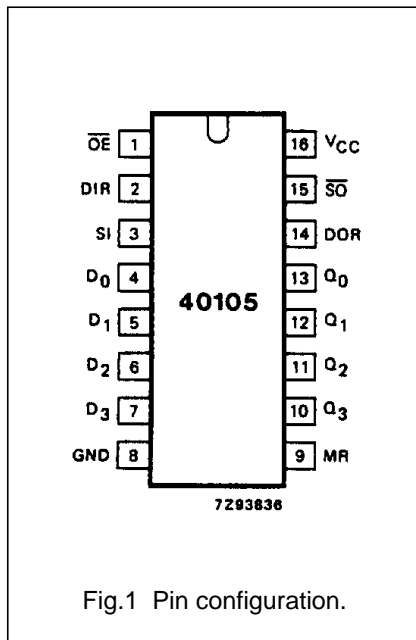
4-bit x 16-word FIFO register

74HC/HCT40105

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
74HC(T)40105N	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1
74HC(T)40105D	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC(T)40105DB	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HC(T)40105PW	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

PIN DESCRIPTION

PIN NO.	SYMBOL	NAME AND FUNCTION
1	$\overline{OE}$	output enable input (active LOW)
2	DIR	data-in ready output
3	SI	shift-in input (LOW-to-HIGH, edge-triggered)
4, 5, 6, 7	D_0 to D_3	parallel data inputs
8	GND	ground (0 V)
9	MR	asynchronous master reset input (active HIGH)
13, 12, 11, 10	Q_0 to Q_3	3-state data outputs
14	DOR	data-out ready output
15	$\overline{SO}$	shift-out input (HIGH-to-LOW, edge-triggered)
16	V_{CC}	positive supply voltage

Fig.1 Pin configuration.

Fig.2 Logic symbol.

Fig.3 IEC logic symbol.

4-bit x 16-word FIFO register

INPUT AND OUTPUTS

Data inputs (D_0 to D_3)

As there is no weighting of the inputs, any input can be assigned as the MSB. The size of the FIFO memory can be reduced from the 4×16 configuration, i.e. 3×16, down to 1×16, by tying unused data input pins to V_{CC} or GND.

Data outputs (Q_0 to Q_3)

As there is no weighting of the outputs, any output can be assigned as the MSB. The size of the FIFO memory can be reduced from the 4×16 configuration as described for data inputs. In a reduced format, the unused data outputs pins must be left open circuit.

Master-reset (MR)

When MR is HIGH, the control functions within the FIFO are cleared, and date content is declared invalid. The data-in ready (DIR) flag is set HIGH and the data-out-ready (DOR) flag is set LOW. The output stage remains in the state of the last word that was shifted out, or in the random state existing at power-up.

Status flag outputs (DIR, DOR)

Indication of the status of the FIFO is given by two status flags, data-in-ready (DIR) and data-out-ready (DOR):

DIR = HIGH indicates the input stage is empty and ready to accept valid data;

DIR = LOW indicates that the FIFO is full or that a previous shift-in operation is not complete (busy);

DOR = HIGH assures valid data is present at the outputs Q_0 to Q_3 (does not indicate that new data is awaiting transfer into the output stage);

DOR = LOW indicates the output stage is busy or there is no valid data.

Shift-in control (SI)

Data is loaded into the input stage on a LOW-to-HIGH transition of SI. It also triggers an automatic data transfer process (ripple through). If SI is held HIGH during reset, data will be loaded at the falling edge of the MR signal.

Shift-out control ($\overline{SO}$)

A HIGH-to-LOW transition of $\overline{SO}$ causes the DOR flags to go LOW. A HIGH-to-LOW transition of $\overline{SO}$ causes upstream data to move into the output stage, and empty locations to move towards the input stage (bubble-up).

Output enable ($\overline{OE}$)

The outputs Q_0 to Q_3 are enabled when $\overline{OE}$ = LOW. When $\overline{OE}$ = HIGH the outputs are in the high impedance OFF-state.

FUNCTIONAL DESCRIPTION

Data input

Following power-up, the master-reset (MR) input is pulsed HIGH to clear the FIFO memory (see Fig.8). The data-in-ready flag (DIR = HIGH) indicates that the FIFO input stage is empty and ready to receive data. When DIR is valid (HIGH), data present at D_0 to D_3 can be shifted-in using the SI control input. With SI = HIGH, data is shifted into the input stage and a busy indication is given by DIR going LOW.

The data remains at the first location in the FIFO until DIR is set to HIGH and data moves through the FIFO to the output stage, or to the last empty location. If the FIFO is not full after the SI pulse, DIR again becomes valid (HIGH) to indicate that space is available in the FIFO. The DIR flag remains LOW if the FIFO is full (see Fig.6). The SI use must be made

LOW in order to complete the shift-in process.

With the FIFO full, SI can be held HIGH until a shift-out ($\overline{SO}$) pulse occurs. Then, following a shift-out of data, an empty location appears at the FIFO input and DIR goes HIGH to allow the next data to be shifted-in. This remains at the first FIFO location until SI goes LOW (see Fig.7).

Data transfer

After data has been transferred from the input stage of the FIFO following SI = LOW, data moves through the FIFO asynchronously and is stacked at the output end of the register. Empty locations appear at the input end of the FIFO as data moves through the device.

Data output

The data-out-ready flag (DOR = HIGH) indicates that there is valid data at the output (Q_0 to Q_3). The initial master-reset at power-on (MR = HIGH) sets DOR to LOW (see Fig.8). After MR = LOW, data shifted into the FIFO moves through to the output stage causing DOR to go HIGH.

As the DOR flag goes HIGH, data can be shifted-out using the $\overline{SO}$ = HIGH, data in the output stage is shifted out and a busy indication is given by DOR going LOW. When $\overline{SO}$ is made LOW, data moves through the FIFO to fill the output stage and an empty location appears at the input stage. When the output stage is filled DOR goes HIGH, but if the last of the valid data has been shifted-out leaving the FIFO empty the DOR flag remains LOW (see Fig.9). With the FIFO empty, the last word that was shifted-out is latched at the output Q_0 to Q_3.

With the FIFO empty, the $\overline{SO}$ input can be held HIGH until the SI control input is used. Following an SI pulse,

data moves through the FIFO to the output stage, resulting in the DOR flag pulsing HIGH and a shift-out of data occurring. The $\overline{SO}$ control must be made LOW before additional data can be shifted-out (see Fig.10).

High-speed burst mode

If it is assumed that the shift-in/shift-out pulses are not applied until the respective status flags are valid, it follows that the shift-in/shift-out rates are determined by the status flags. However, without the status flags a high-speed burst mode can be implemented. In this mode, the burst-in/ burst-out rates are determined by the pulse widths of the shift-in/shift-out inputs and burst rates of 35 MHz can be obtained. Shift

pulses can be applied without regard to the status flags but shift-in pulses that would overflow the storage capacity of the FIFO are not allowed (see Figs 11 and 12).

Expanded format

With the addition of a logic gate, the FIFO is easily expanded to increase word length (see Fig.17). The basic operation and timing are identical to a single FIFO, with the exception of an additional gate delay on the flag outputs. If during application, the following occurs:

• SI is held HIGH when the FIFO is empty, some additional logic is required to produce a composite DIR pulse (see Figs 7 and 18).

Due to the part-to-part spread of the ripple through time, the SI signals of $FIFO_A$ and $FIFO_B$ will not always coincide and the AND-gate will not produce a composite flag signal. The solution is given in Fig.18.

The "40105" is easily cascaded to increase the word capacity and no external components are needed. In the cascaded configuration, all necessary communications and timing are performed by the FIFOs. The intercommunication speed is determined by the minimum flag pulse widths and the flag delays. The data rate of cascaded devices is typically 25 MHz. Word-capacity can be expanded to and beyond 32-words $\times$ 4-bits (see Fig.19).

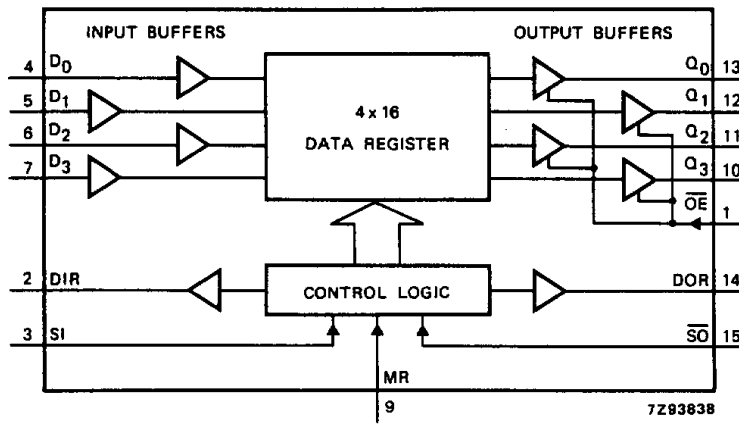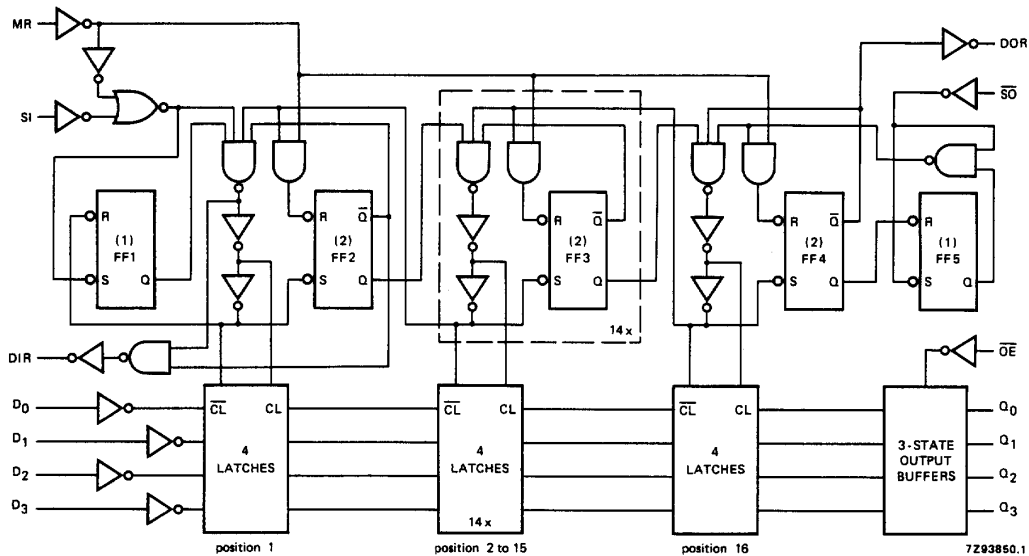4-bit x 16-word FIFO register

74HC/HCT40105

Fig.4 Functional diagram.

(see control flip-flops)

(1) LOW on $\overline{S}$ input of FF1, and FF5 will set Q output to HIGH independent of state on $\overline{R}$ input.

(2) LOW on $\overline{R}$ input of FF2, FF3 and FF4 will set Q output to LOW independent of state on $\overline{S}$ input.

Fig.5 Logic diagram.

4-bit x 16-word FIFO register

74HC/HCT40105

DC CHARACTERISTICS FOR 74HC

For the DC characteristics see *"74HC/HCT/HCU/HCMOS Logic Family Specifications"*.

Output capability: standard
I_{CC} category: MSI

AC CHARACTERISTICS FOR 74HC

GND = 0 V; t_f = t_f = 6 ns; C_L = 50 pF

SYMBOL	PARAMETER	T_{amb} (°C)							UNIT	TEST CONDITIONS	
		74HC								V_{CC} (V)	WAVEFORMS
		+25			−40 to +85		−40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
t_{PHL}/ t_{PLH}	propagation delay MR to DIR, DOR		52	175		220		265	ns	2.0	Fig.8
			19	35		44		53		4.5	
			15	30		37		45		6.0	
t_{PHL}	propagation delay SI to DIR		52	210		265		315	ns	2.0	Fig.6
			19	42		53		63		4.5	
			15	36		45		54		6.0	
t_{PHL}	propagation delay $\overline{SO}$ to DOR		55	210		265		315	ns	2.0	Fig.9
			20	42		53		63		4.5	
			16	36		45		54		6.0	
t_{PHL}/ t_{PLH}	propagation delay $\overline{SO}$ to Q_n		116	400		500		600	ns	2.0	Fig.14
			42	80		100		120		4.5	
			34	68		85		102		6.0	
t_{PLH}	propagation delay/ ripple through delay SI to DOR		564	2000		2500		3000	ns	2.0	Fig.10
			205	400		500		600		4.5	
			165	340		425		510		6.0	
t_{PLH}	propagation delay/ bubble-up delay $\overline{SO}$ to DIR		701	2500		3125		3750	ns	2.0	Fig.7
			255	500		625		750		4.5	
			204	425		532		638		6.0	
t_{PZH}/ t_{PZL}	3-state output enable time $\overline{OE}$ to Q_n		41	150		190		225	ns	2.0	Fig.16
			15	30		38		45		4.5	
			12	26		33		38		6.0	
t_{PHZ}/ t_{PLZ}	3-state output disable time $\overline{OE}$ to Q_n		41	140		175		210	ns	2.0	Fig.16
			15	28		35		42		4.5	
			12	24		30		36		6.0	
t_{THL}/ t_{TLH}	output transition time		19	75		95		110	ns	2.0	Fig.14
			7	15		19		22		4.5	
			6	13		16		19		6.0	
t_W	SI pulse width HIGH or LOW	80	19		100		120		ns	2.0	Fig.6
		16	7		20		24			4.5	
		14	6		17		20			6.0	

4-bit x 16-word FIFO register

74HC/HCT40105

SYMBOL	PARAMETER	T_{amb} (°C) 74HC +25			T_{amb} (°C) 74HC −40 to +85		T_{amb} (°C) 74HC −40 to +125		UNIT	V_{CC} (V)	WAVEFORMS
		min.	typ.	max.	min.	max.	min.	max.			
t_W	$\overline{SO}$ pulse width HIGH or LOW	120 24 20	39 14 11		150 30 26		180 36 31		ns	2.0 4.5 6.0	Fig.9
t_W	DIR pulse width HIGH	12 6 5	58 21 17	180 36 31	10 5 4	225 45 38	10 5 4	270 54 46	ns	2.0 4.5 6.0	Fig.7
t_W	DOR pulse width LOW	12 6 5	55 20 16	170 34 29	10 5 4	215 43 37	10 5 4	255 51 43	ns	2.0 4.5 6.0	Fig.9
t_W	MR pulse width HIGH	80 16 14	22 8 6		100 20 17		120 24 20		ns	2.0 4.5 6.0	Fig.8
t_{rem}	removal time MR to SI	50 10 9	14 5 4		65 13 11		75 15 13		ns	2.0 4.5 6.0	Fig.15
t_{su}	set-up time D_n to SI	−5 −5 −5	−39 −14 −11		−5 −5 −5		−5 −5 −5		ns	2.0 4.5 6.0	Fig.13
t_h	hold time D_n to SI	125 25 21	44 16 13		155 31 26		190 38 32		ns	2.0 4.5 6.0	Fig.13
f_{max}	maximum pulse frequency SI, $\overline{SO}$ using flags or burst mode	3.6 18 21	10 30 36		2.8 14 16		2.4 12 14		MHz	2.0 4.5 6.0	Fig.6, 9, 11 and 12
f_{max}	maximum pulse frequency SI, $\overline{SO}$ cascaded	3.6 18 21	10 30 36		2.8 14 16		2.4 12 14		MHz	2.0 4.5 6.0	Figs 6 and 9

4-bit x 16-word FIFO register

DC CHARACTERISTICS FOR 74HCT

For the DC characteristics see *"74HC/HCT/HCU/HCMOS Logic Family Specifications"*.

Output capability: standard
I_{CC} category: MSI

Note to HCT types

The value of additional quiescent supply current (ΔI_{CC}) for a unit load of 1 is given in the family specifications.

To determine ΔI_{CC} per input, multiply this value by the unit load coefficient shown in the table below.

INPUT	UNIT LOAD COEFFICIENT
$\overline{OE}$	0.75
SI	0.40
D_n	0.30
MR	1.50
$\overline{SO}$	0.40

AC CHARACTERISTICS FOR 74HCT

GND = 0 V; $t_f = t_f$ = 6 ns; C_L = 50 pF

SYMBOL	PARAMETER	T_{amb} (°C)						UNIT	TEST CONDITIONS	
		74HCT							V_{CC} (V)	WAVEFORMS
		+25			−40 to +85		−40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
t_{PHL}/ t_{PLH}	propagation delay MR to DIR, DOR		18	35		44		53	ns	4.5	Fig.8
t_{PHL}	propagation delay SI to DIR		21	42		53		63	ns	4.5	Fig.6
t_{PHL}	propagation delay $\overline{SO}$ to DOR		20	42		53		63	ns	4.5	Fig.9
t_{PHL}/ t_{PLH}	propagation delay $\overline{SO}$ to Q_n		40	80		100		120	ns	4.5	Fig.14
t_{PLH}	propagation delay/ ripple through delay SI to DOR		188	400		500		600	ns	4.5	Fig.10
t_{PLH}	propagation delay/ bubble-up delay $\overline{SO}$ to DIR		244	500		625		750	ns	4.5	Fig.7
t_{PZH}/ t_{PZL}	3-state output enable time $\overline{OE}$ to Q_n		18	35		44		53	ns	4.5	Fig.16
t_{PHZ}/ t_{PLZ}	3-state output disable time $\overline{OE}$ to Q_n		15	30		38		45	ns	4.5	Fig.16
t_{THL}/ t_{TLH}	output transition time		7	15		19		22	ns	4.5	Fig.14

4-bit x 16-word FIFO register

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SYMBOL	PARAMETER	T_{amb} (°C)							UNIT	TEST CONDITIONS	
		74HCT								V_{CC} (V)	WAVEFORMS
		+25			−40 to +85		−40 to +125				
		min.	typ.	max.	min.	max.	min.	max.			
t_W	SI pulse width HIGH or LOW	16	6		20		24		ns	4.5	Fig.6
t_W	$\overline{SO}$ pulse width HIGH or LOW	16	7		20		24		ns	4.5	Fig.9
t_W	DIR pulse width HIGH or LOW	6	20	34	5	43	5	51	ns	4.5	Fig.7
t_W	DOR pulse width HIGH or LOW	6	19	34	5	43	5	51	ns	4.5	Fig.9
t_W	MR pulse width HIGH	16	7		20		24		ns	4.5	Fig.8
t_{rem}	removal time MR to SI	15	7		19		22		ns	4.5	Fig.15
t_{su}	set-up time D_n to SI	−5	−14		−4		−4		ns	4.5	Fig.13
t_h	hold time D_n to SI	27	16		34		41		ns	4.5	Fig.13
f_{max}	maximum pulse frequency SI, $\overline{SO}$ using flags or burst mode		28		12		10		MHz	4.5	Fig.6, 9, 11 and 12
f_{max}	maximum pulse frequency SI, $\overline{SO}$ cascaded		28		12		10		MHz	4.5	Figs 6 and 9

4-bit x 16-word FIFO register

AC WAVEFORMS

Shifting in sequence FIFO empty to FIFO full

(1) HC : V_M = 50%; V_I = GND to V_{CC}.
HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.6   Waveforms showing the SI input to DIR output propagation delay. The SI pulse width and SI maximum pulse frequency.
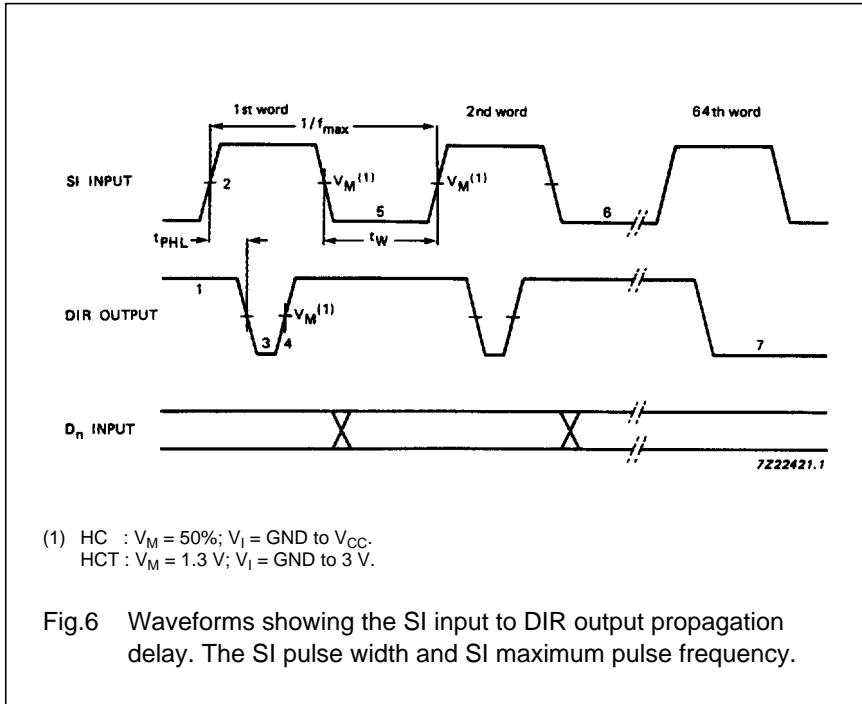
Notes to Fig.6

1. DIR initially HIGH; FIFO is prepared for valid data.
2. SI set HIGH; data loaded into input stage.
3. DIR drops LOW, input stage "busy".
4. DIR goes HIGH, status flag indicates FIFO prepared for additional data; data from first location "ripple through".
5. SI set LOW; necessary to complete shift-in process.
6. Repeat process to load 2nd word through to 16th word into FIFO.
7. DIR remains LOW: with attempt to shift into full FIFO, no data transfer occurs.

With FIFO full; SI held HIGH in anticipation of empty location

(1) HC : V_M = 50%; V_I = GND to V_{CC}.
HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.7   Waveforms showing bubble-up delay, $\overline{SO}$ input to DIR output and DIR output pulse width.
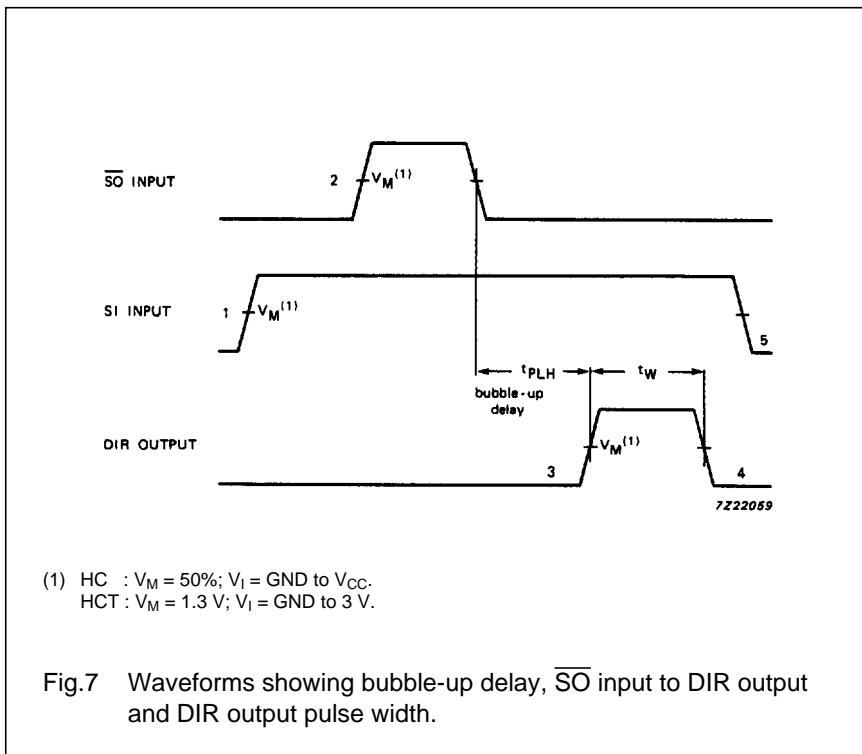
Notes to Fig.7

1. FIFO is initially, shift-in is held HIGH.
2. $\overline{SO}$ pulse; data in the output stage is unloaded, "bubble-up process of empty locations begins".
3. DIR HIGH; when empty location reached input stage, flag indicates FIFO is prepared for data input.
4. DIR returns to LOW; FIFO is full again.
5. SI brought LOW; necessary to complete whidt-in process, DIR remains LOW, because FIFO is full.

4-bit x 16-word FIFO register

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Master reset applied with FIFO full

(1) HC : $V_M = 50\%$; $V_I = $ GND to V_{CC}.
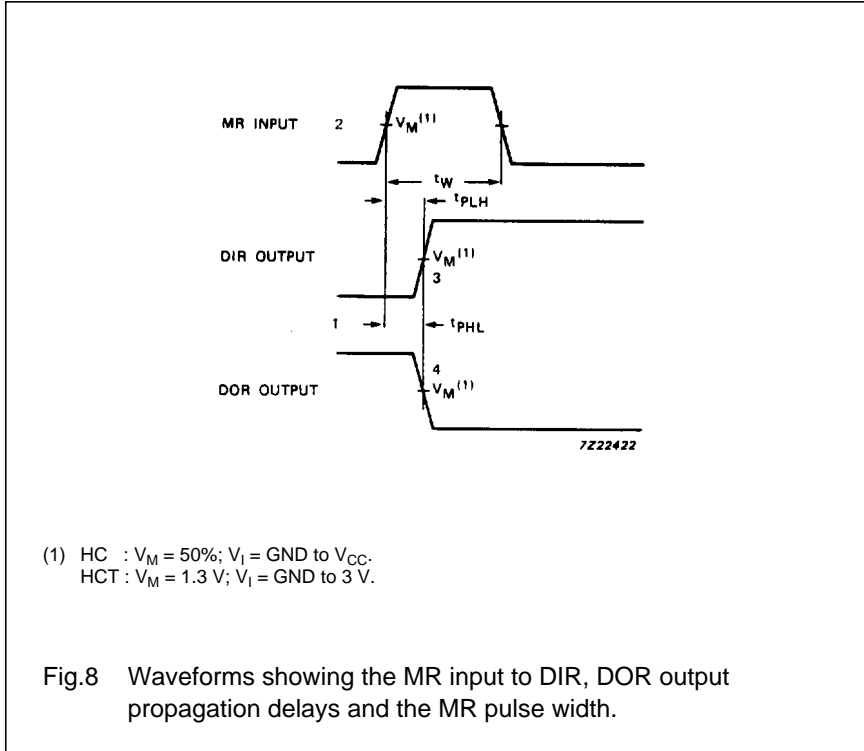   HCT : $V_M = 1.3$ V; $V_I = $ GND to 3 V.

Fig.8   Waveforms showing the MR input to DIR, DOR output
        propagation delays and the MR pulse width.

Notes to Fig.8

1. DIR LOW, output ready HIGH; assume FIFO is full.

2. MR pulse HIGH; clears FIFO.

3. DIR goes HIGH; flag indicates input prepared for valid data.

4. DOR drops LOW; flag indicates FIFO empty.

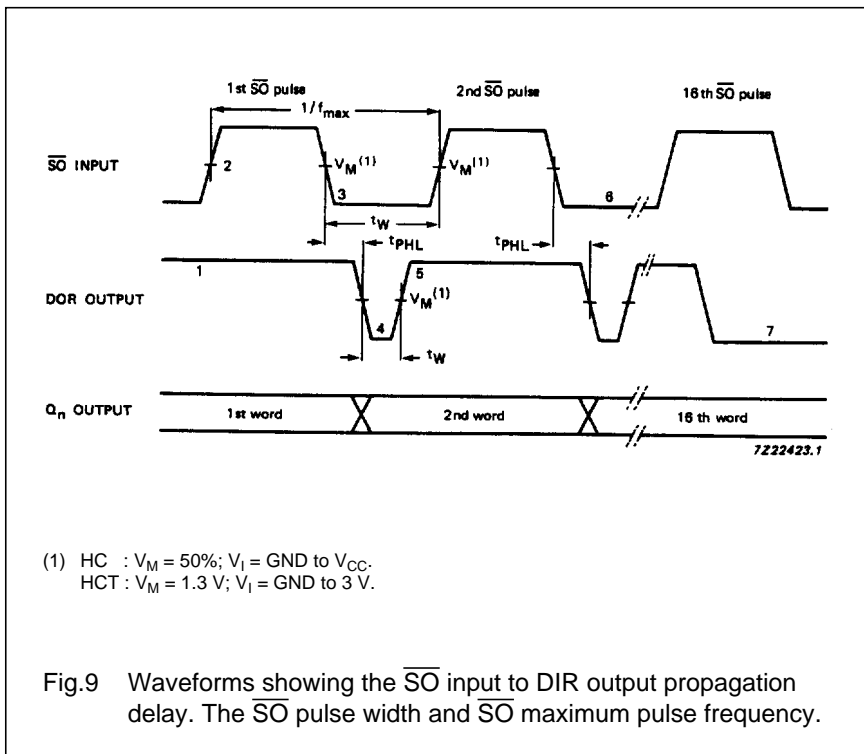**Shifting out sequence; FIFO full to FIFO empty**

(1) HC : $V_M = 50\%$; $V_I = $ GND to V_{CC}.
    HCT : $V_M = 1.3$ V; $V_I = $ GND to 3 V.

Fig.9   Waveforms showing the $\overline{SO}$ input to DIR output propagation
        delay. The $\overline{SO}$ pulse width and $\overline{SO}$ maximum pulse frequency.

Notes to Fig.9

1. DOR HIGH; no data transfer in progress, valid data is present at output stage.

2. $\overline{SO}$ set HIGH.

3. $\overline{SO}$ is set LOW; data in the input stage is unloaded, and new data replaces it as empty location "bubbles-up" to input stage.

4. DOR drops LOW; output stage "busy".

5. DOR goes HIGH; transfer process completed, valid data present at output after the specified propagation delay.

6. Repeat process to unloaded the 3rd through to the 16th word from FIFO.

7. DOR remains LOW; FIFO is empty.

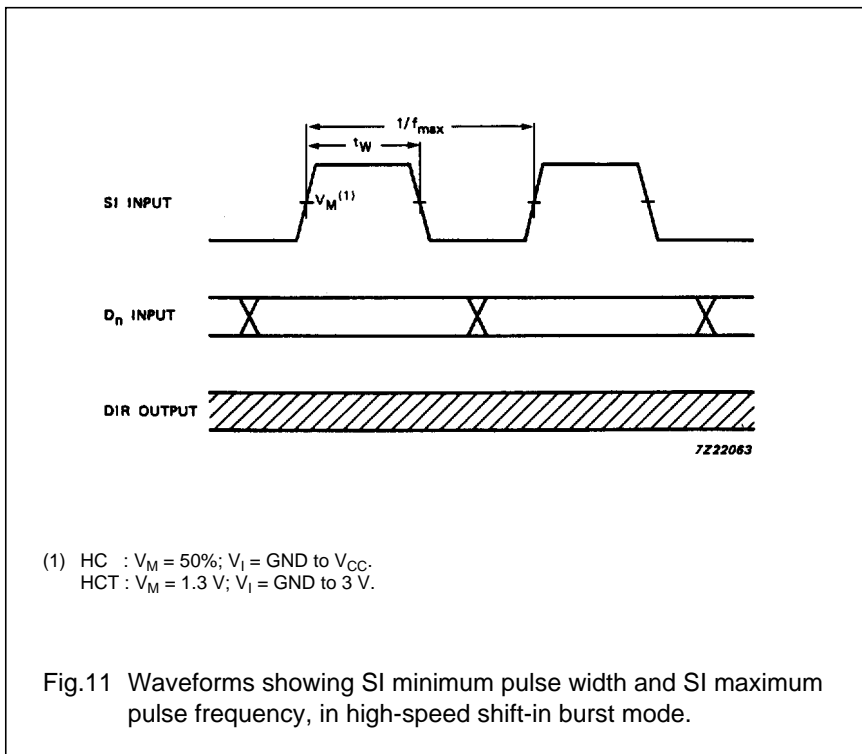## 4-bit x 16-word FIFO register

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With FIFO empty; $\overline{SO}$ is held HIGH in anticipation

(1) HC : V_M = 50%; V_I = GND to V_{CC}.
HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.10 Waveforms showing ripple through delay SI input to DOR output and propagation delay from the DOR pulse to the Q_n output.
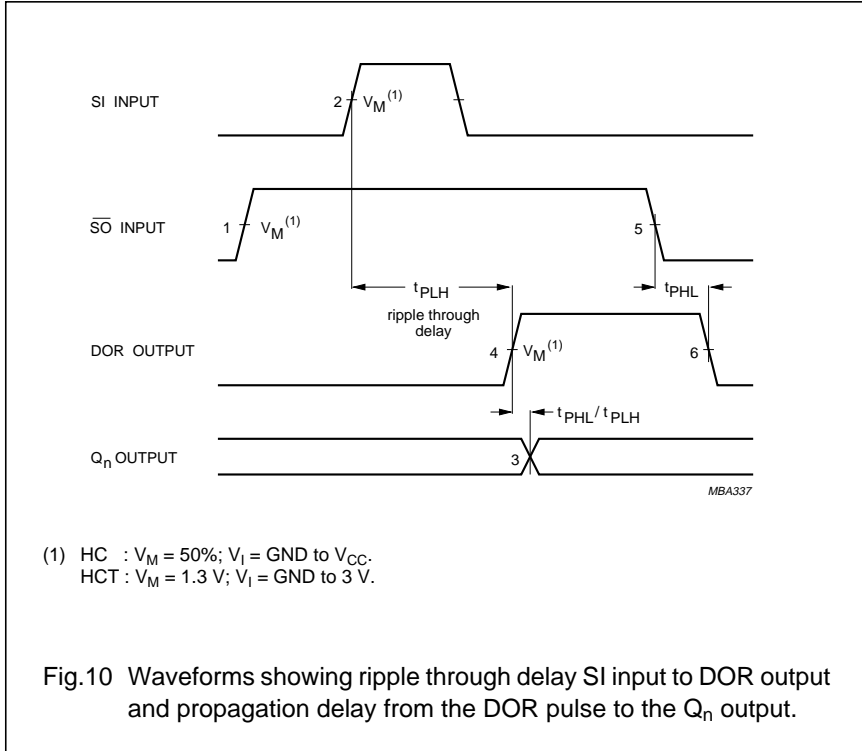
Notes to Fig.10

1. FIFO is initially empty, $\overline{SO}$ is held HIGH.

2. SI pulse; loads data into FIFO and initiates ripple through process.

3. DOR flag signals the arrival of valid data at the output stage.

4. Output transition; data arrives at output stage after the specified propagation delay between the rising edge of the DOR pulse to the Q_n output.

5. $\overline{SO}$ set LOW; necessary to complete shift-out process. DOR remains LOW, because FIFO is empty.

6. DOR goes LOW; FIFO is empty again.

Shift-in operation; high-speed burst mode

(1) HC : V_M = 50%; V_I = GND to V_{CC}.
HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.11 Waveforms showing SI minimum pulse width and SI maximum pulse frequency, in high-speed shift-in burst mode.
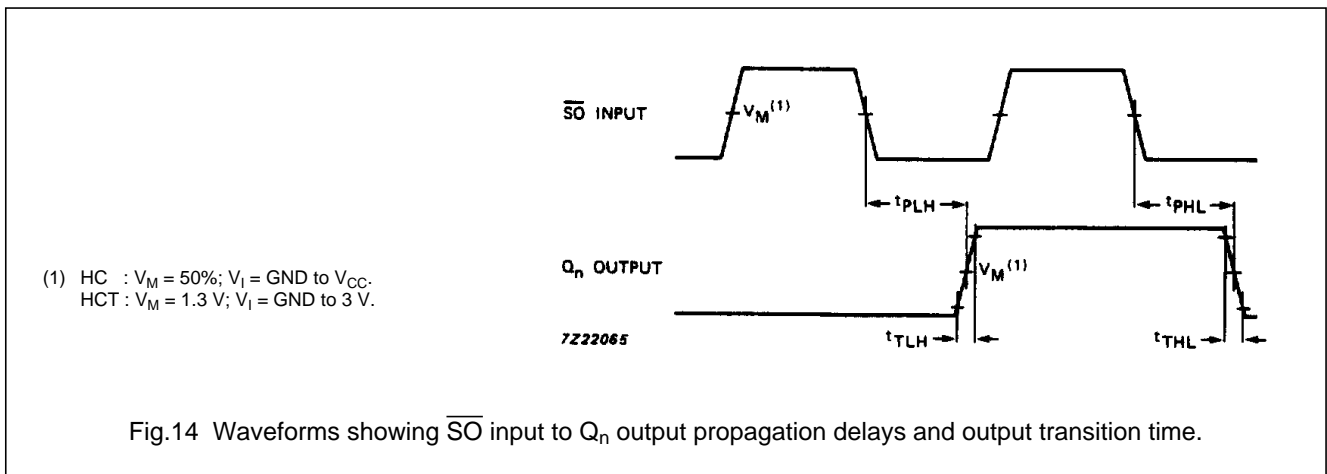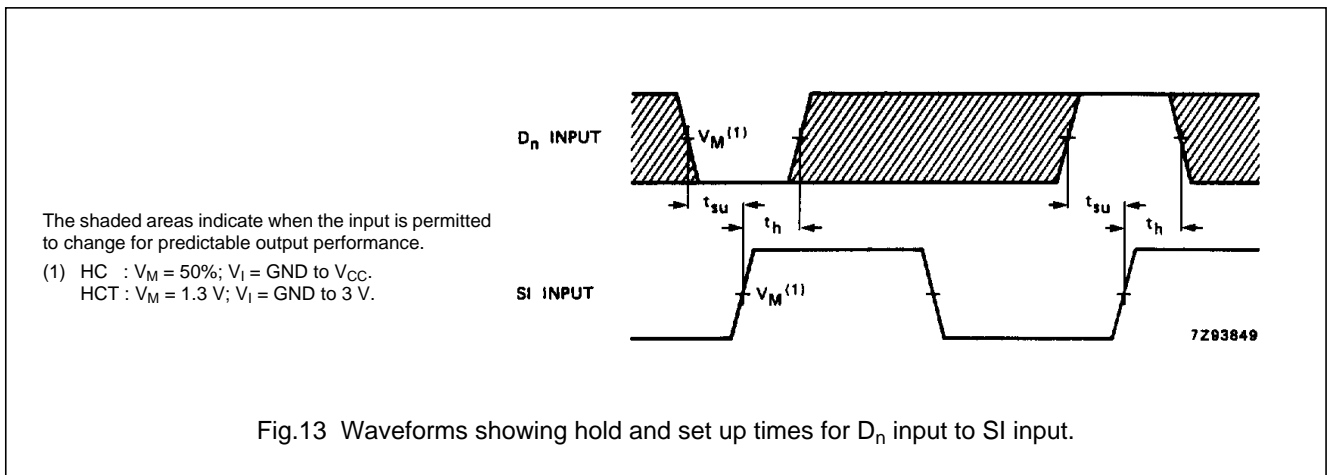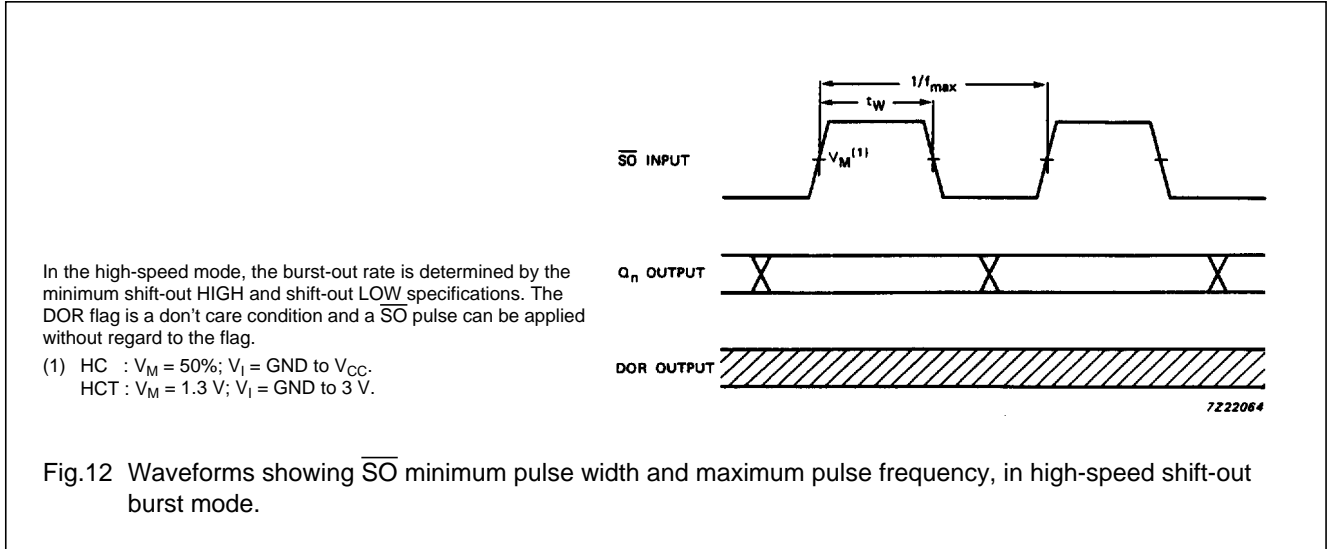
Note to Fig.11

In the high-speed mode, the burst-in rate is determined by the minimum shift-in HIGH and shift-in LOW specifications. The DIR status flag is a don't care condition, and a shift-in pulse can be applied regardless of the flag. A SI pulse which would overflow the storage capacity of the FIFO is ignored.
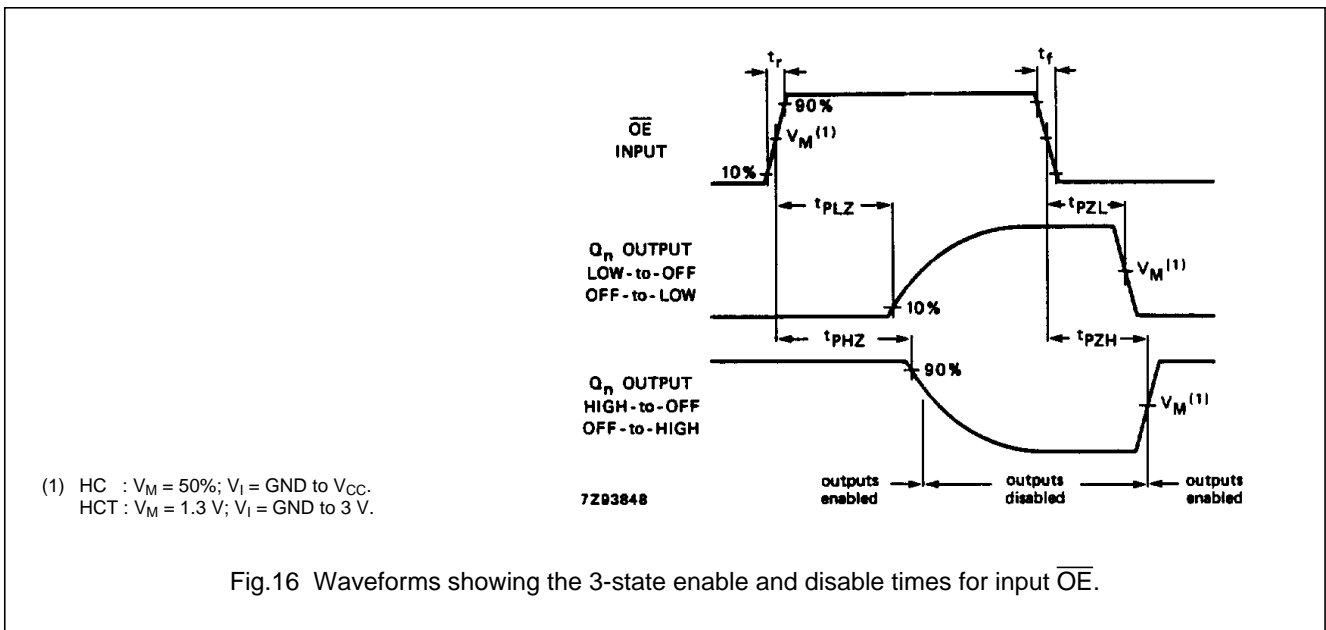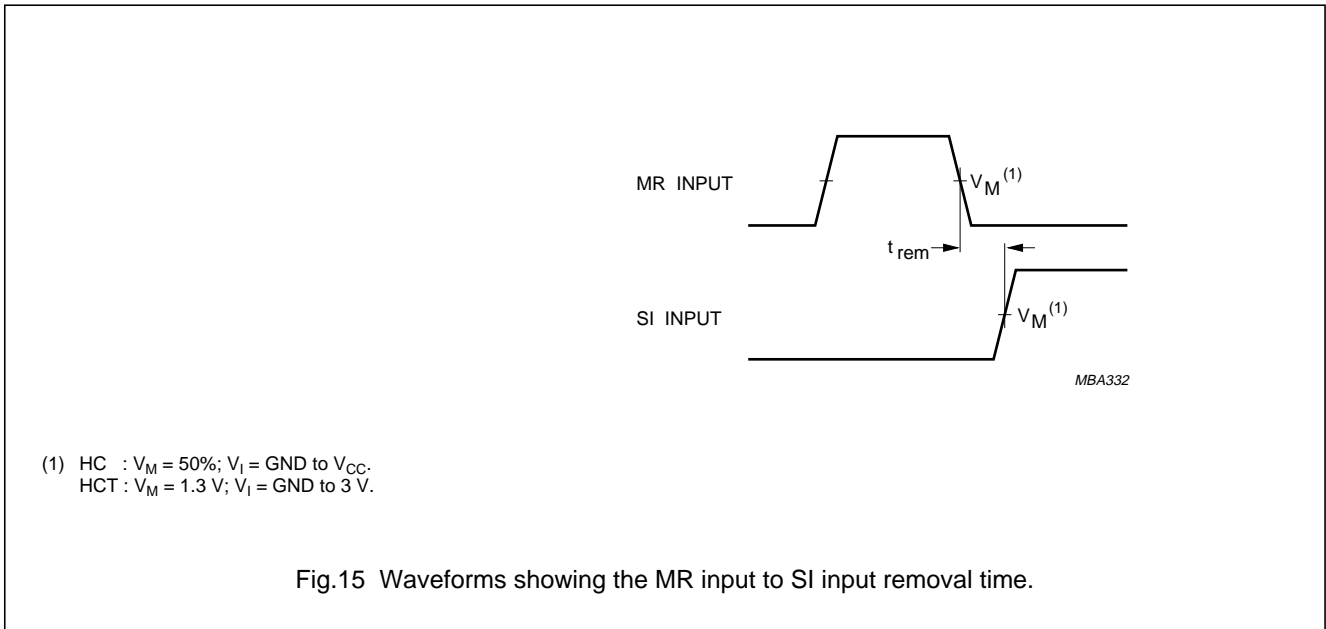
4-bit x 16-word FIFO register

74HC/HCT40105

Shift-out operation; high-speed burst mode

In the high-speed mode, the burst-out rate is determined by the minimum shift-out HIGH and shift-out LOW specifications. The DOR flag is a don't care condition and a $\overline{SO}$ pulse can be applied without regard to the flag.

(1) HC   : $V_M = 50\%$; V_I = GND to V_{CC}.
     HCT : $V_M = 1.3$ V; V_I = GND to 3 V.

Fig.12 Waveforms showing $\overline{SO}$ minimum pulse width and maximum pulse frequency, in high-speed shift-out burst mode.

The shaded areas indicate when the input is permitted to change for predictable output performance.

(1) HC   : $V_M = 50\%$; V_I = GND to V_{CC}.
     HCT : $V_M = 1.3$ V; V_I = GND to 3 V.

Fig.13 Waveforms showing hold and set up times for D_n input to SI input.

(1) HC   : $V_M = 50\%$; V_I = GND to V_{CC}.
     HCT : $V_M = 1.3$ V; V_I = GND to 3 V.

Fig.14 Waveforms showing $\overline{SO}$ input to Q_n output propagation delays and output transition time.

(1) HC   : V_M = 50%; V_I = GND to V_{CC}.
     HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.15 Waveforms showing the MR input to SI input removal time.

(1) HC   : V_M = 50%; V_I = GND to V_{CC}.
     HCT : V_M = 1.3 V; V_I = GND to 3 V.

Fig.16 Waveforms showing the 3-state enable and disable times for input $\overline{OE}$.

4-bit x 16-word FIFO register

74HC/HCT40105

APPLICATION INFORMATION

The PC74HC/HCT40105 is easily expanded to increase word length. Composite DIR and DOR flags are formed with the addition of an AND gate. The basic operation and timing are identical to a single FIFO, with the exception of an added gate delay on the flags.
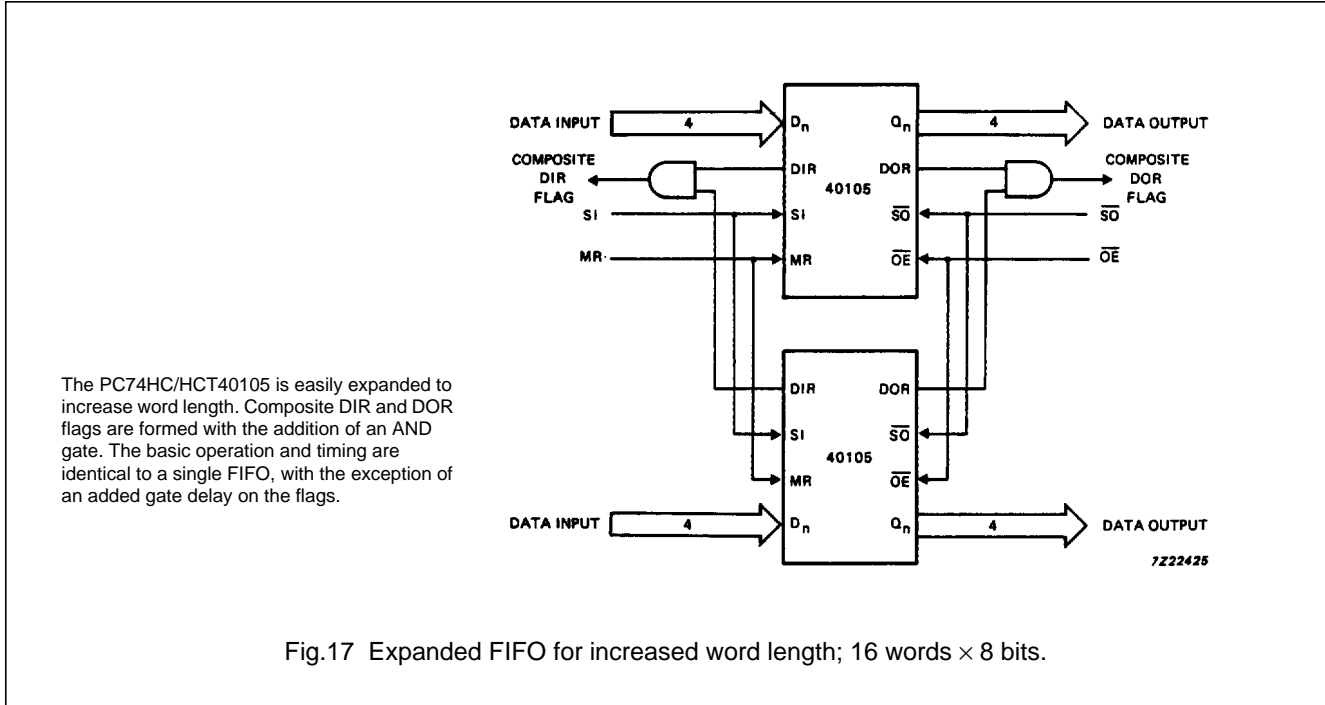
Fig.17 Expanded FIFO for increased word length; 16 words × 8 bits.

This circuit is only required if the SI input is constantly held HIGH, when the FIFO is empty and the automatic shift-in cycles are started (see Fig.7).
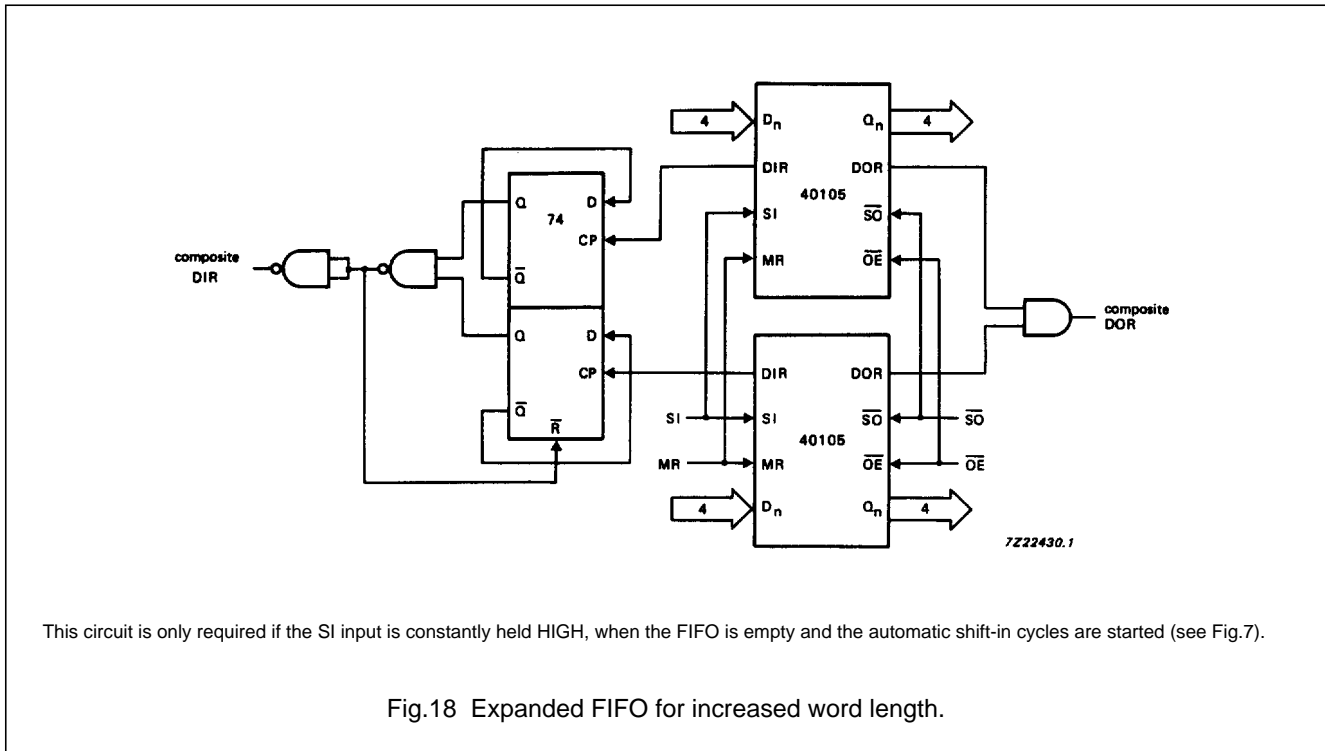
Fig.18 Expanded FIFO for increased word length.

4-bit x 16-word FIFO register

Expanded format

Fig.19 shows two cascaded FIFOs providing a capacity of 32 words × 4 bits

Fig.20 shows the signals on the nodes of both FIFOs after the application of a SI pulse, when both FIFOs are initially empty. After a rippled through delay, date arrives at the output of $FIFO_A$. Due to $\overline{SO}_A$ being HIGH, a DOR pulse is generated. The requirements of SI_B and D_{nB} are satisfied by the DOR_A pulse width and the timing between the rising edge of DOR_A and Q_{nA}. After a second ripple through delay, data arrives at the output of $FIFO_B$.

Fig.21 shows the signals on the nodes of both FIFOs after the application of a $\overline{SO}_R$ pulse, when both FIFOs are initially full. After a bubble-up delay a DIR_R pulse is generated, which acts as a $\overline{SO}_A$ pulse for $FIFO_A$. One word is transferred from the output of $FIFO_A$ to the input of $FIFO_B$. The requirements of the $\overline{SO}_A$ pulse for $FIFO_A$ is satisfied by the pulse width of DOR_B. After a second bubble-up delay an empty space arrives at D_{nA}, at which time DIR_A goes HIGH.

Fig.22 shows the waveforms at all external nodes of both FIFOs during a complete shift-in and shift-out sequence.
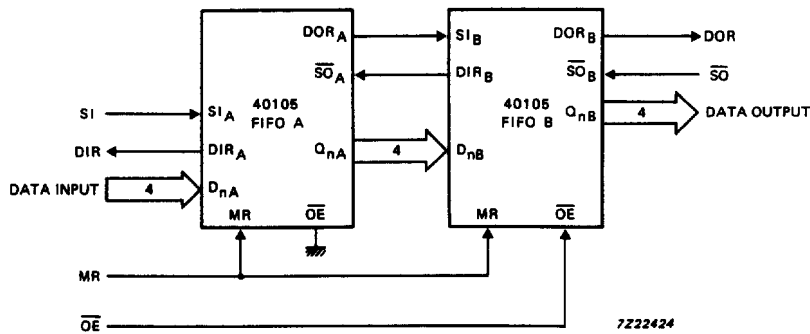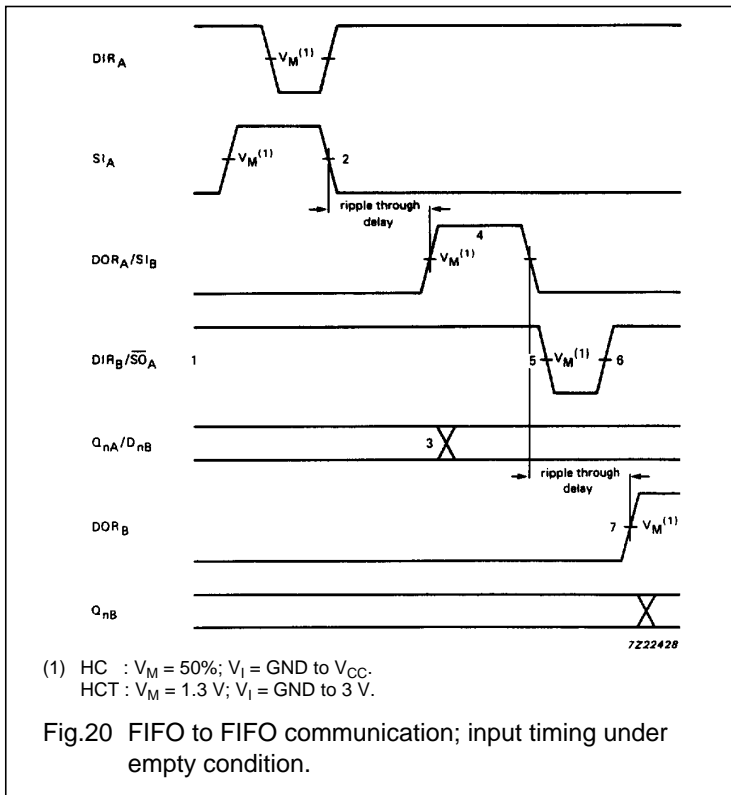

The PC7HC/HCT40105 is easily cascaded to increase word capacity without any external circuitry. In cascaded format, all necessary communications are handled by the FIFOs. Figs 17 and 19 demonstrate the intercommunication timing between $FIFO_A$ and $FIFO_B$. Fig.22 gives an overview of pulse and timing of two cascaded FIFOs, when shifted full and shifted empty again.

Fig.19 Cascading for increased word capacity; 32 words × 4 bits.

4-bit x 16-word FIFO register

74HC/HCT40105

(1) HC : $V_M = 50\%$; $V_I = $ GND to V_{CC}.
  HCT : $V_M = 1.3$ V; $V_I = $ GND to 3 V.

Fig.20 FIFO to FIFO communication; input timing under
empty condition.

(1) HC : $V_M = 50\%$; $V_I = $ GND to V_{CC}.
  HCT : $V_M = 1.3$ V; $V_I = $ GND to 3 V.

Fig.21 FIFO to FIFO communication; output timing under
full condition.

Notes to Fig.20

1. $FIFO_A$ and $FIFO_B$ initially empty, $\overline{SO}_A$ held
   HIGH in anticipation of data.

2. Load one word into $FIFO_A$; SI pulse applied,
   results in DIR pulse.

3. Data out $_A$/data in $_B$ transition; valid data
   arrives at $FIFO_A$ output stage after a specified
   delay of the DOR flag, meeting data input
   set-up requirements of $FIFO_B$.

4. DOR_A and SI_B pulse HIGH; (ripple through
   delay after SI_A LOW) data is unloaded from
   $FIFO_A$ as a result of the data output ready
   pulse, data is shifted into $FIFO_B$.

5. DIR_B and $\overline{SO}_A$ go LOW; flag indicates input
   stage of $FIFO_B$ is busy, shift-out of $FIFO_A$ is
   complete.

6. DIR_B and $\overline{SO}_A$ go HIGH automatically; the
   input stage of $FIFO_B$ is again able to receive
   data, $\overline{SO}$ is held HIGH in anticipation of
   additional data.

7. DOR_B goes HIGH; (ripple through delay after
   SI_B LOW) valid data is present one
   propagation delay later at the $FIFO_B$ output
   stage.
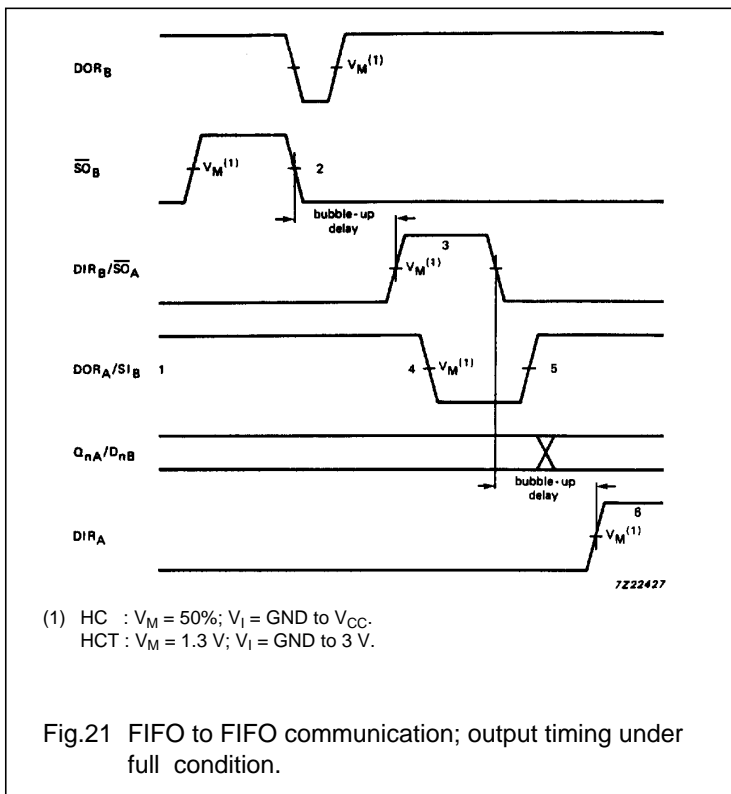
Notes to Fig.21

1. $FIFO_A$ and $FIFO_B$ initially empty, SI_B held
   HIGH in anticipation of shifting in new data as
   empty location bubbles-up.

2. Unload one word into $FIFO_B$; $\overline{SO}$ pulse
   applied, results in DOR pulse.

3. DIR_B and $\overline{SO}_A$ pulse HIGH; (bubble-up delay
   after $\overline{SO}_B$ LOW) data is loaded into $FIFO_B$ as
   a result of the DIR pulse, data is shifted out of
   $FIFO_A$.

4. DOR_A and SI_B go LOW; flag indicates the
   output stage of $FIFO_A$ is busy, shift-in to
   $FIFO_R$ is complete.

5. DOR_A and SI_B go HIGH; flag indicates valid
   data is again available at $FIFO_A$ output stage,
   SI_B is held HIGH, awaiting bubble-up of
   empty location.

6. DIR_A goes HIGH; (bubble-up delay after
   $\overline{SO}_A$ LOW) an empty location is present at
   input stage of $FIFO_A$.

4-bit x 16-word FIFO register
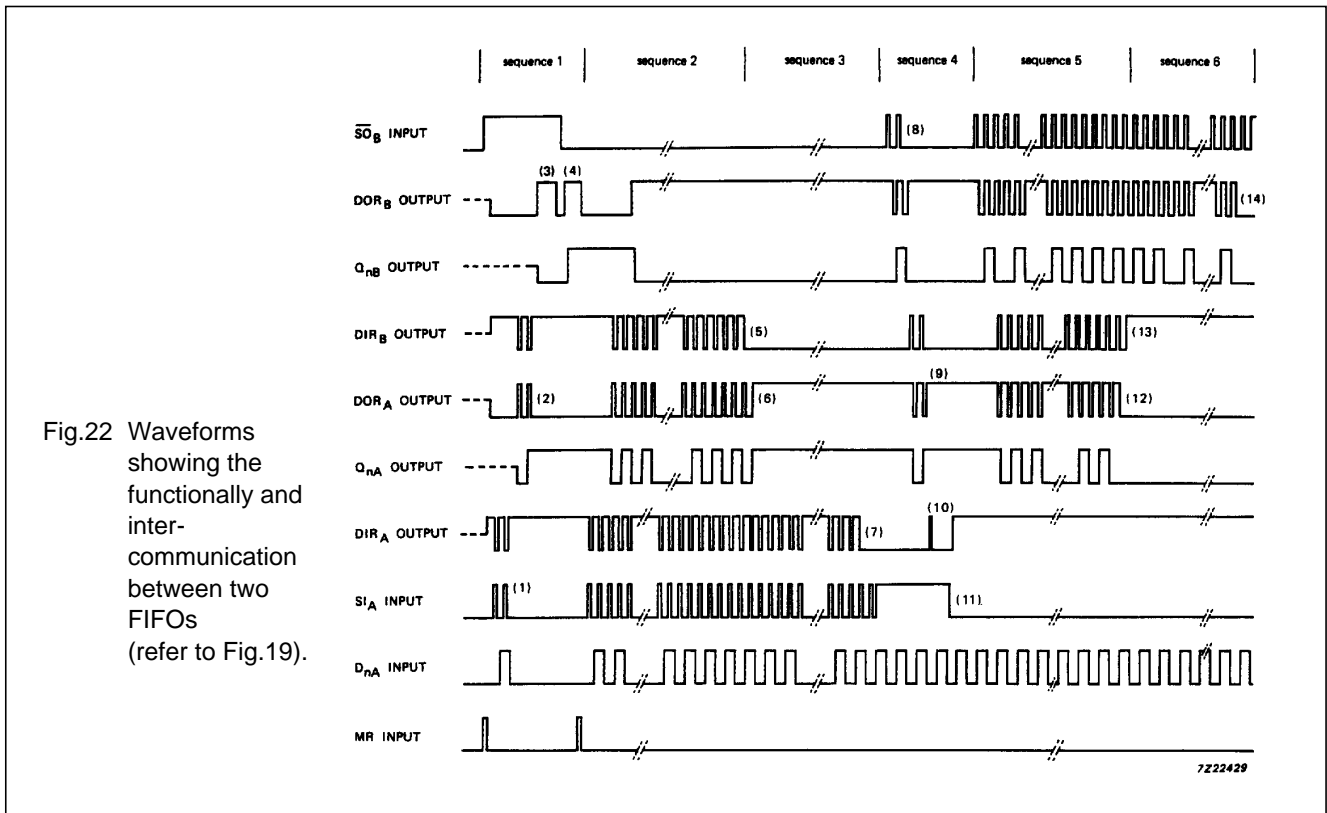
74HC/HCT40105

Fig.22 Waveforms showing the functionally and inter-communication between two FIFOs (refer to Fig.19).

Note to Fig.22

Sequence 1 (Both FIFOs empty, starting shift-in process):
After a MR pulse has been applied $FIFO_A$ and $FIFO_B$ are empty. The DOR flags of $FIFO_A$ and $FIFO_B$ go LOW due to no valid data being present at the outputs. The DIR flags are set HIGH due to the FIFOs being ready to accept data. $\overline{SO}_B$ is held HIGH and two SI_A pulses are applied (1). These pulses allow two data words to ripple through to the output stage of $FIFO_A$ and to the input stage of $FIFO_B$ (2). When data arrives at the output of $FIFO_B$, a DOR_B pulse is generated (3). When $\overline{SO}_B$ goes LOW, the first bit is shifted out and a second bit ripples through to the output after which DOR_B goes HIGH (4).

Sequence 2 ($FIFO_B$ runs full):
After the MR pulse, a series of 16 SI pulses are applied. When 16 words are shifted in, DIR_B remains LOW due to $FIFO_B$ being full (5). DOR_A goes LOW due to $FIFO_A$ being empty.

Sequence 3 ($FIFO_A$ runs full):
When 17 words are shifted in, DOR_A remains HIGH due to valid data remaining at the output of $FIFO_A$. Q_{nA} remains HIGH, being the polarity of the 17th data word (6). After the 32th SI pulse, DIR remains LOW and both FIFOs are full (7). Additional pulses have no effect.

Sequence 4 (Both FIFOs full, starting shift-out process):
SI_A is held HIGH and two $\overline{SO}_B$ pulses are applied (8). These pulses shift out two words and thus allow empty locations to bubble-up to the input stage of $FIFO_B$, and proceed to $FIFO_A$ (9). When the first empty location arrives at the input of $FIFO_A$, a DIR_A pulse is generated (10) and a new word is shifted into $FIFO_A$. SI_A is made LOW and now the second empty location reaches the input stage of $FIFO_A$, after which DIR_A remains HIGH (11).

Sequence 5 ($FIFO_A$ runs empty):
At the start of sequence 5 $FIFO_A$ contains 15 valid words due to two words being shifted out and one word being shifted in sequence 4. An additional series of $\overline{SO}_B$ pulses are applied. After 15 $\overline{SO}_B$ pulses, all words from $FIFO_A$ are shifted into $FIFO_B$. DOR_A remains LOW (12).

Sequence 6 ($FIFO_B$ runs empty):
After the next $\overline{SO}_B$ pulse, DIR_B remains HIGH due to the input stage of $FIFO_B$ being empty (13). After another 15 $\overline{SO}_B$ pulses, DOR_B remains LOW due to both FIFOs being empty (14). Additional $\overline{SO}_B$ pulses have no effect. The last word remains available at the output Q_n.
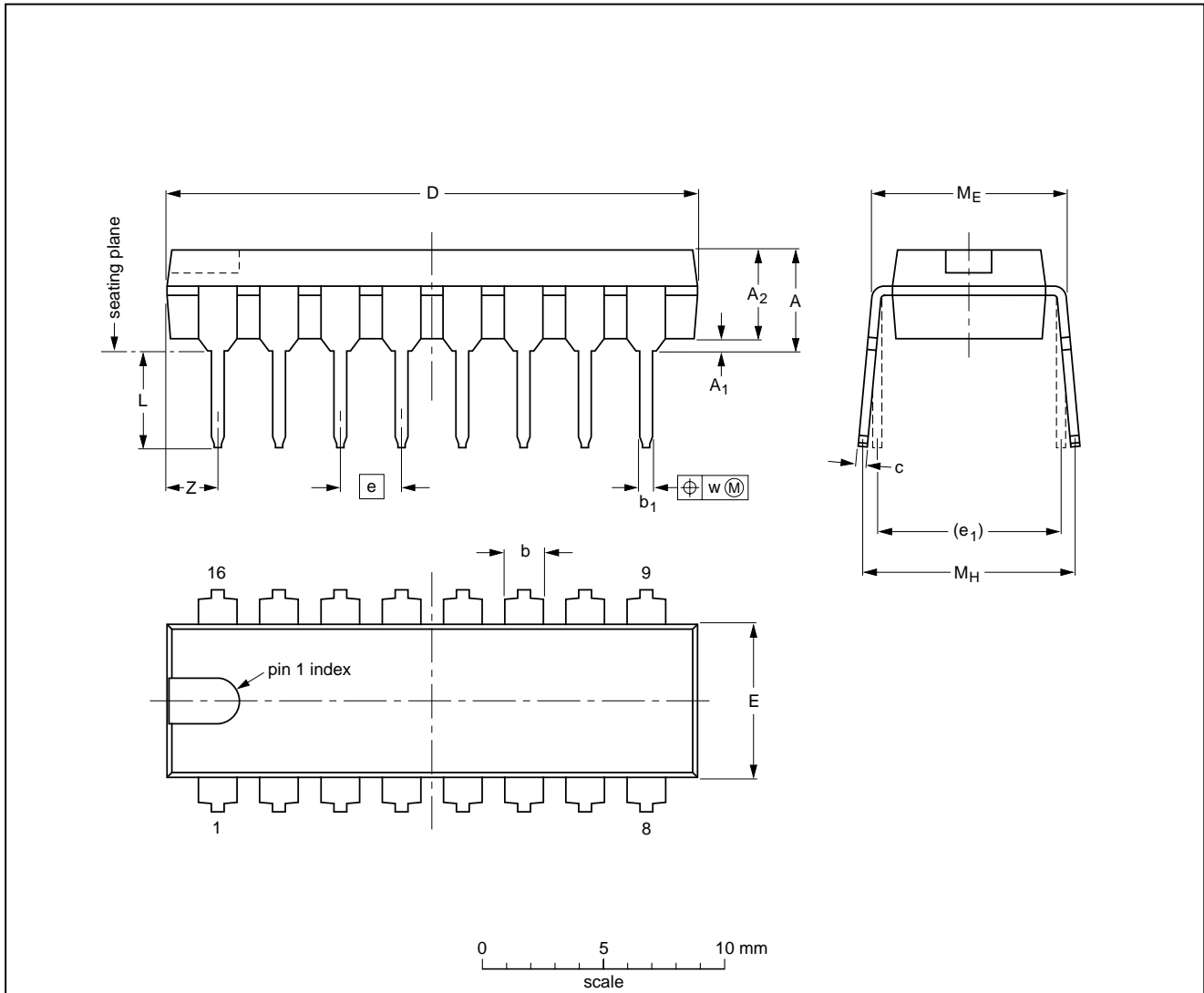
4-bit x 16-word FIFO register

74HC/HCT40105

PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1

pin 1 index

0   5   10 mm

scale

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A$_1$ min.	A$_2$ max.	b	b$_1$	c	D [1]	E [1]	e	e$_1$	L	M$_E$	M$_H$	w	Z [1] max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

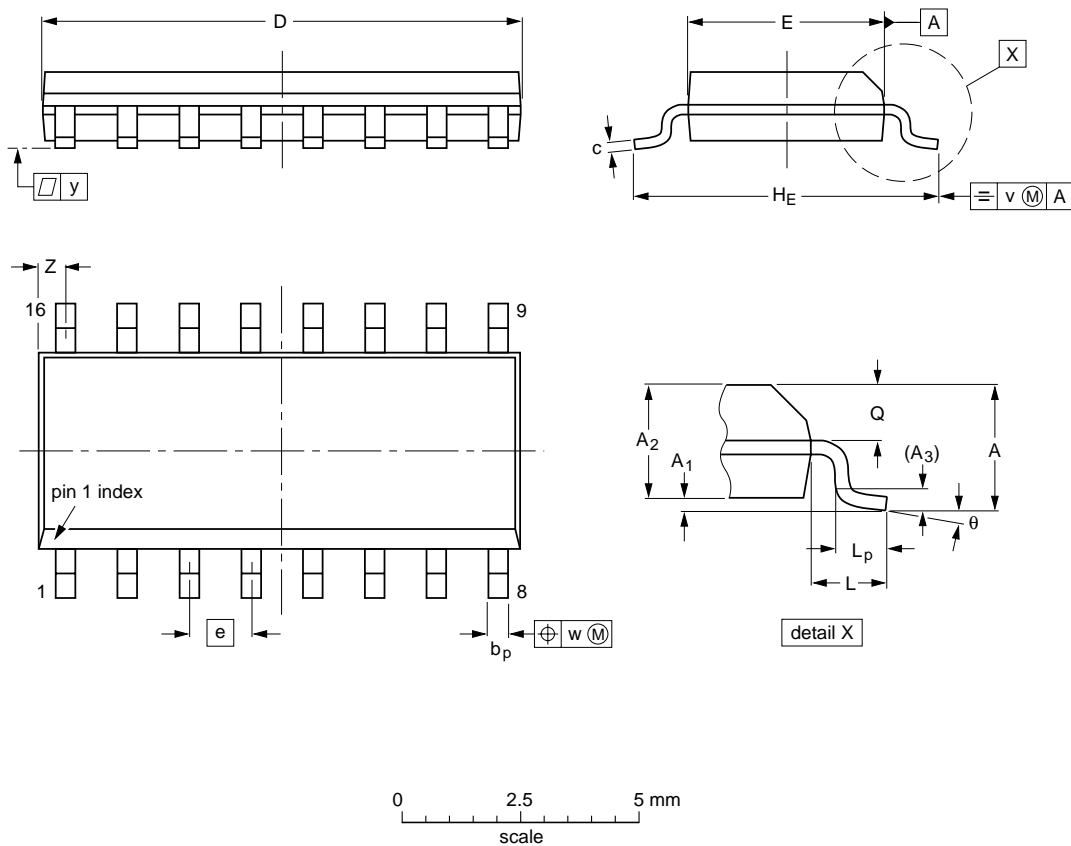1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02 95-01-19

4-bit x 16-word FIFO register

74HC/HCT40105

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1


```
0          2.5          5 mm
|__|__|__|__|__|__|__|__|__|
          scale
```

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A₁	A₂	A₃	bₚ	c	D(1)	E(1)	e	HₑE	L	Lₚ	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

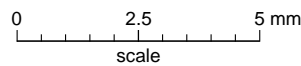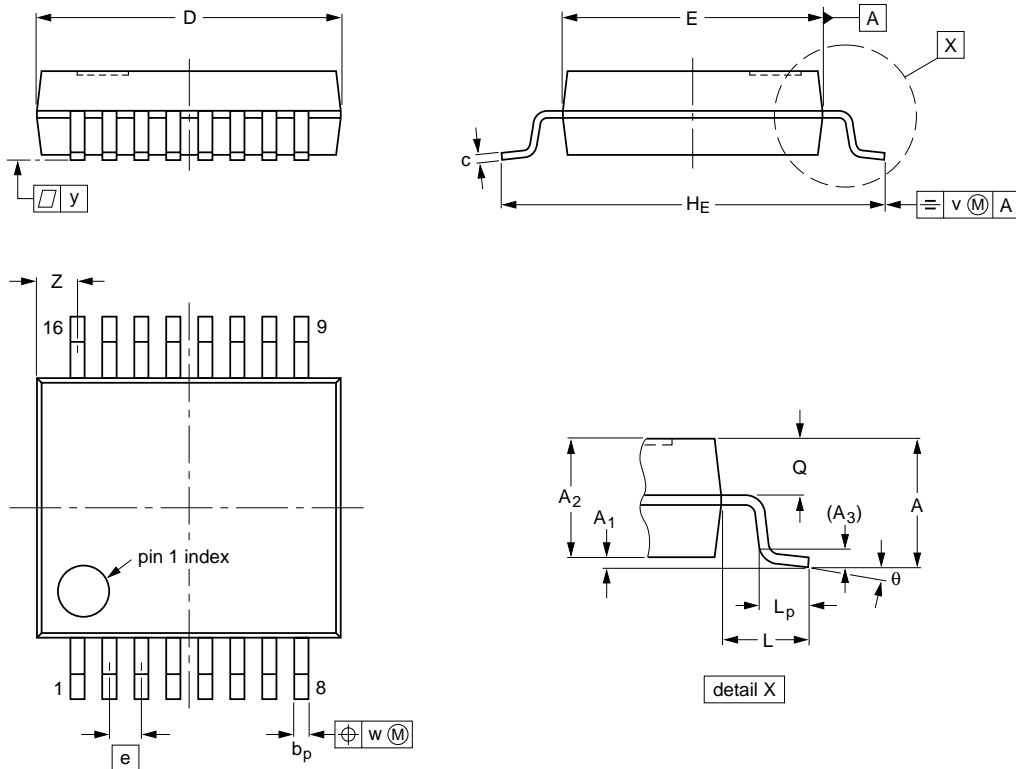1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

4-bit x 16-word FIFO register

74HC/HCT40105

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A₁	A₂	A₃	bₚ	c	D⁽¹⁾	E⁽¹⁾	e	H_E	L	Lₚ	Q	v	w	y	Z⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8° 0°

Note

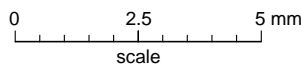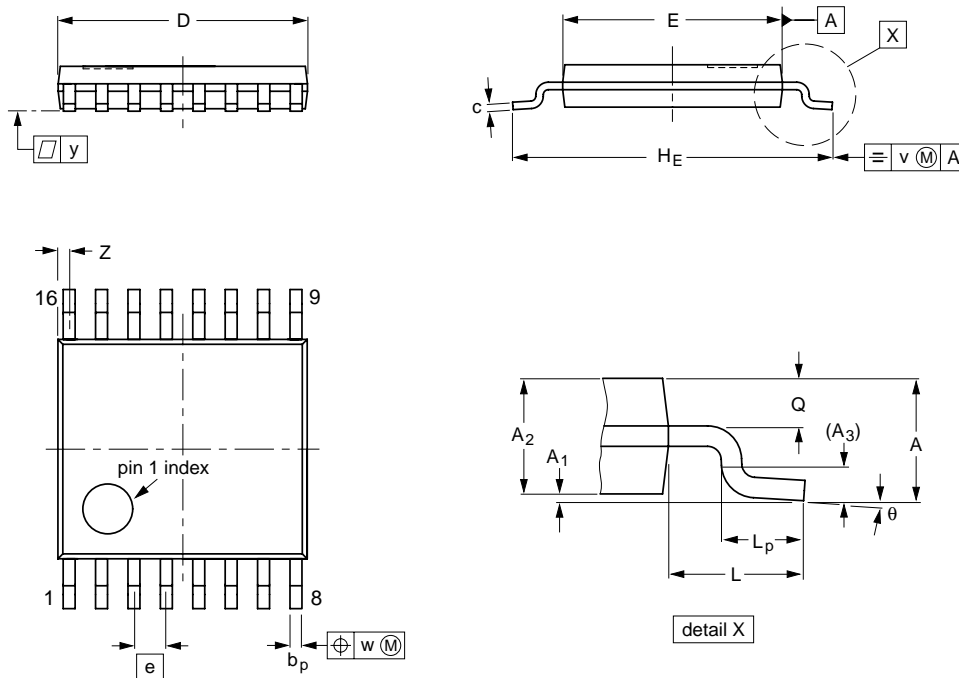1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT338-1		MO-150AC				~~94-01-14~~ 95-02-04

4-bit x 16-word FIFO register

74HC/HCT40105

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

pin 1 index

detail X

```
0        2.5        5 mm
scale
```

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A₁	A₂	A₃	b_p	c	D [1]	E [2]	e	H_E	L	L_p	Q	v	w	y	Z [1]	θ
mm	1.10	0.15 / 0.05	0.95 / 0.80	0.25	0.30 / 0.19	0.2 / 0.1	5.1 / 4.9	4.5 / 4.3	0.65	6.6 / 6.2	1.0	0.75 / 0.50	0.4 / 0.3	0.2	0.13	0.1	0.40 / 0.06	8° / 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT403-1		MO-153				~~94-07-12~~ 95-04-04

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\,max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

SO, SSOP and TSSOP

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO, SSOP and TSSOP packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method.

Typical reflow temperatures range from 215 to 250 °C. Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

WAVE SOLDERING

Wave soldering can be used for all SO packages. Wave soldering is **not** recommended for SSOP and TSSOP packages, because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

If wave soldering is used - **and cannot be avoided for SSOP and TSSOP packages** - the following conditions must be observed:

• A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.

• The longitudinal axis of the package footprint must be parallel to the solder flow and must incorporate solder thieves at the downstream end.

Even with these conditions:

• **Only consider wave soldering SSOP packages that have a body width of 4.4 mm, that is SSOP16 (SOT369-1) or SSOP20 (SOT266-1).**

• **Do not consider wave soldering TSSOP packages with 48 leads or more, that is TSSOP48 (SOT362-1) and TSSOP56 (SOT364-1).**

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

4-bit x 16-word FIFO register

74HC/HCT40105

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.